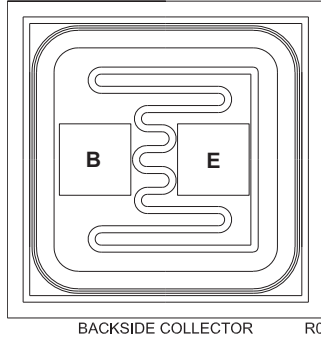


# CP336V-2N5551

## NPN - High Voltage Transistor Die

The CP336V-2N5551 is a silicon NPN transistor designed for high voltage, general purpose applications.



### MECHANICAL SPECIFICATIONS:

Die Size	17.3 x 17.3 MILS
Die Thickness	7.1 MILS
Base Bonding Pad Size	3.9 x 3.9 MILS
Emitter Bonding Pad Size	3.9 x 3.9 MILS
Top Side Metalization	Al-Si – 17,000Å
Back Side Metalization	Au – 9,000Å
Scribe Alley Width	1.8 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	57,735

### MAXIMUM RATINGS: (T<sub>A</sub>=25°C)

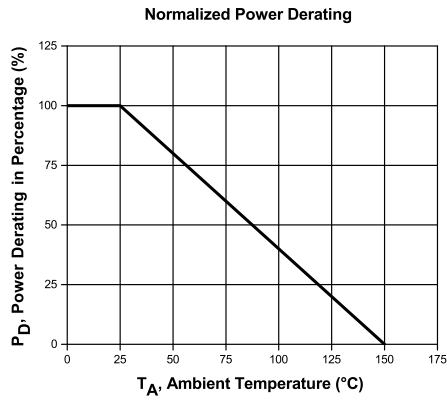
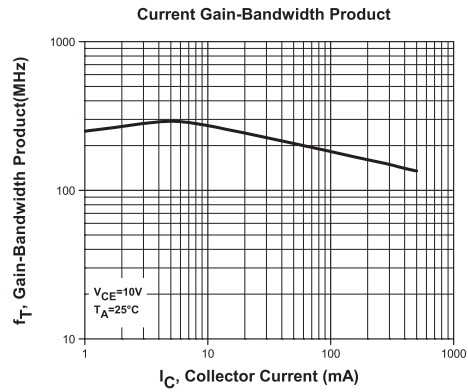
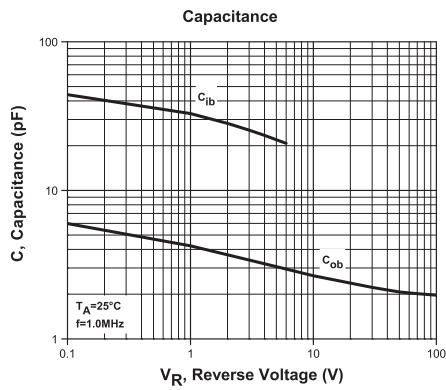
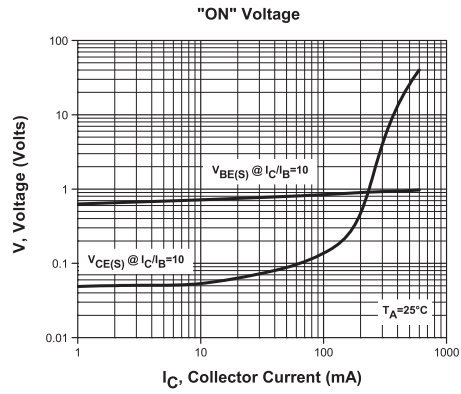
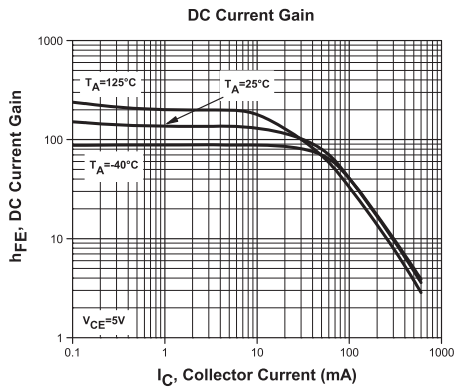
	SYMBOL		UNITS
Collector-Base Voltage	V <sub>CB0</sub>	180	V
Collector-Emitter Voltage	V <sub>CEO</sub>	160	V
Emitter-Base Voltage	V <sub>EBO</sub>	6.0	V
Continuous Collector Current	I <sub>C</sub>	600	mA
Operating and Storage Junction Temperature	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C

### ELECTRICAL CHARACTERISTICS: (T<sub>A</sub>=25°C)

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I <sub>CBO</sub>	V <sub>CB</sub> =120V		50	nA
I <sub>EBO</sub>	V <sub>EB</sub> =4.0V		50	nA
BV <sub>CB0</sub>	I <sub>C</sub> =100μA	180		V
BV <sub>CEO</sub>	I <sub>C</sub> =1.0mA	160		V
BV <sub>EBO</sub>	I <sub>E</sub> =10μA	6.0		V
V <sub>CE(SAT)</sub>	I <sub>C</sub> =10mA, I <sub>B</sub> =1.0mA		0.15	V
V <sub>CE(SAT)</sub>	I <sub>C</sub> =50mA, I <sub>B</sub> =5.0mA		0.20	V
V <sub>BE(SAT)</sub>	I <sub>C</sub> =50mA, I <sub>B</sub> =5.0mA		1.0	V
h <sub>FE</sub>	V <sub>CE</sub> =5.0V, I <sub>C</sub> =1.0mA	80		
h <sub>FE</sub>	V <sub>CE</sub> =5.0V, I <sub>C</sub> =10mA	80	250	
h <sub>FE</sub>	V <sub>CE</sub> =5.0V, I <sub>C</sub> =50mA	30		
f <sub>T</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =10mA, f=100MHz	100	300	MHz
C <sub>ob</sub>	V <sub>CB</sub> =10V, I <sub>E</sub> =0, f=1.0MHz		6.0	pF

# CP336V-2N5551

## Typical Electrical Characteristics



## OUTSTANDING SUPPORT AND SUPERIOR SERVICES



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### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

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### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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### CONTACT US

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